

05-14-01

PATENT

A

Case Docket No. ADTST.029AUS

Date: May 12, 2001

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ASSISTANT COMMISSIONER FOR PATENTS
WASHINGTON, D.C. 20231

ATTENTION: APPLICATION BRANCH

Sir:

Transmitted herewith for filing is the patent application of

Inventor(s): **Rochit Rajsuman**

For: **METHOD OF EVALUATING CORE BASED SYSTEM-ON-A-CHIP (SOC) AND STRUCTURE OF
SOC INCORPORATING SAME**

Enclosed are:

- (X) 6 sheet(s) of drawings.
- (X) 13 pages of specification, claims and abstract.
- (X) **UNSIGNED** declaration and power of attorney.
- (X) Return prepaid postcard.

CLAIMS AS FILED

FOR	NUMBER FILED	NUMBER EXTRA	RATE	FEE
Basic Fee			\$710	\$710
Total Claims	9 - 20 =	0 ×	\$18	\$0
Independent Claims	3 - 3 =	0 ×	\$80	\$0
If application contains any multiple dependent claims(s), then add			\$270	\$0
TOTAL FILING FEE				\$710

- (X) A check in the amount of \$710 to cover the filing fee is enclosed.

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May 12, 2001

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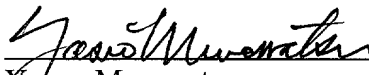
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Attorney Docket No. : ADTST.029AUS
Applicant(s) : Rochit Rajsuman
For : METHOD OF EVALUATING CORE
BASED : SYSTEM-ON-A-CHIP (SOC) AND
STRUCTURE OF SOC INCORPORATING
SAME
Attorney : Yasuo Muramatsu
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I hereby certify that the accompanying

Transmittal; a patent application in 13 pages of specification and 6 sheets of drawings; a check of \$710 for filing fee; unsigned declaration and power of attorney: Return Prepaid Postcard

are being deposited with the United States Postal Service "Express Mail Post Office to Addressee" service under 37 CFR 1.10 on the date indicated above and are addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.


Yasuo Muramatsu